

GHB-GW20-R

Features

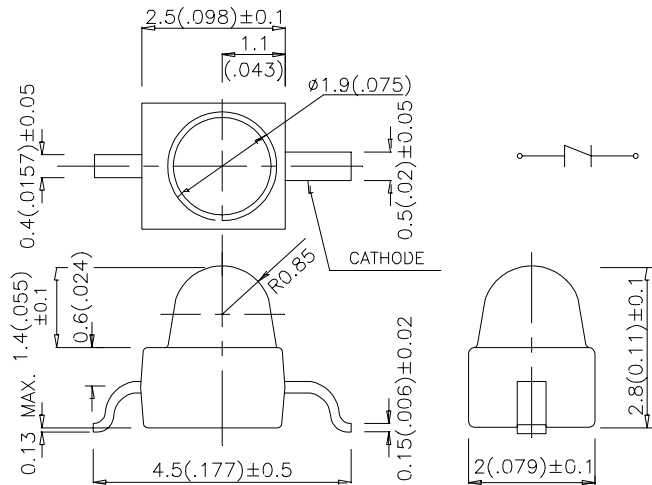
- ▣ SUBMINIATURE PACKAGE.
- ▣ WIDE VIEWING ANGLE.
- ▣ LONG LIFE - SOLID STATE RELIABILITY.
- ▣ LOW PACKAGE PROFILE.
- ▣ PACKAGE: 1000PCS / REEL.

Package Dimensions

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

SUBMINIATURE SOLID STATE LAMP



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is 0.25(0.01") unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	
GHB-GW20-R	HYPER RED (InGaAlP)	WATER CLEAR	280	660	20°

Note:

- 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25 C

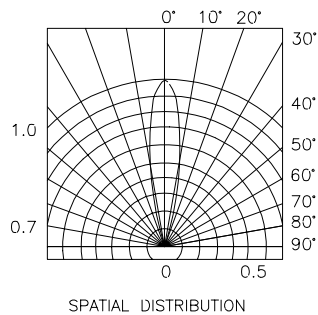
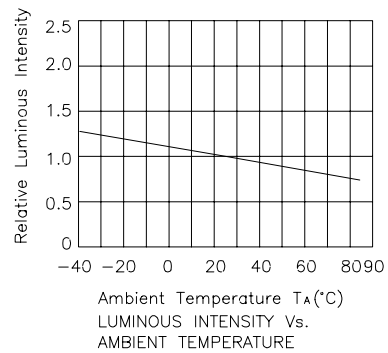
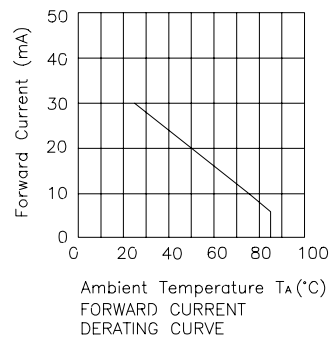
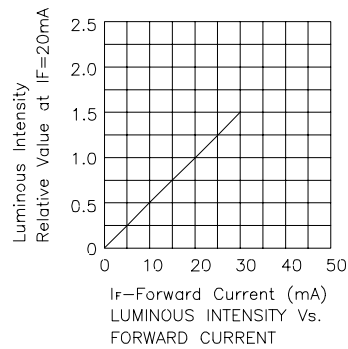
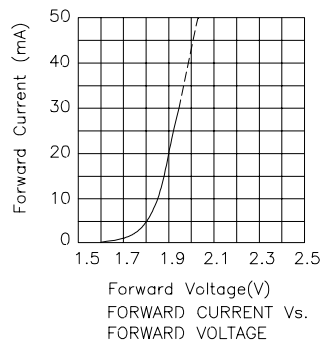
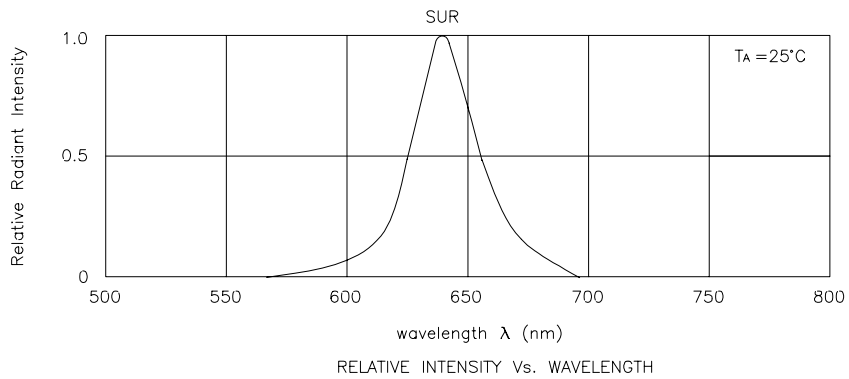
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
peak	Peak Wavelength	Hyper Red	640		nm	I _F =20mA
D	Dominate Wavelength	Hyper Red	628		nm	I _F =20mA
1/2	Spectral Line Half-width	Hyper Red	27		nm	I _F =20mA
C	Capacitance	Hyper Red	45		pF	V _F =0V,f=1MHz
V _F	Forward Voltage	Hyper Red	1.9	2.5	V	I _F =20mA
I _R	Reverse Current	Hyper Red		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25 C

Parameter	Hyper Red	Units
Power dissipation	170	m W
DC Forward Current	30	m A
Peak Forward Current [1]	185	m A
Reverse Voltage	5	V
Operating/Storage Temperature	-40 C To +85 C	

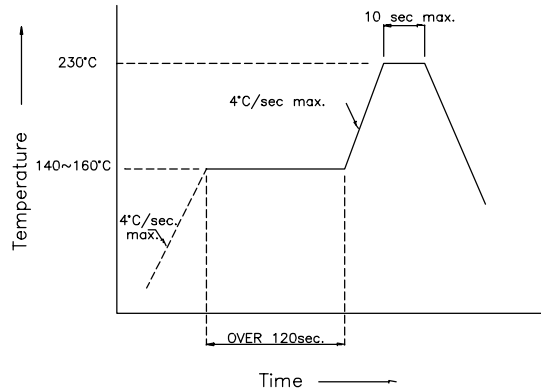
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

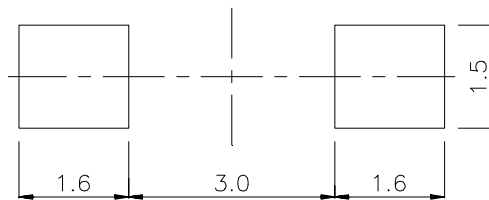


SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

